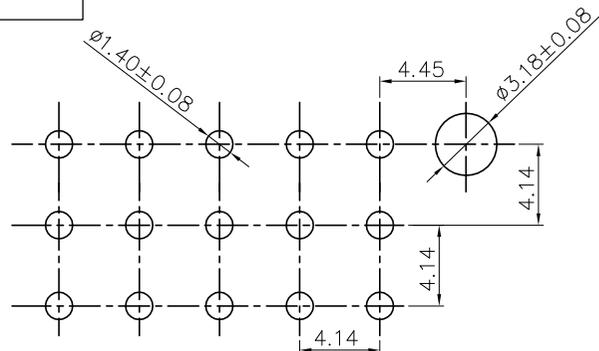
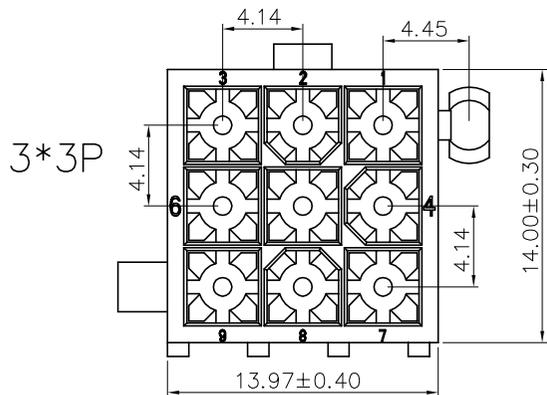


The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements

RoHS

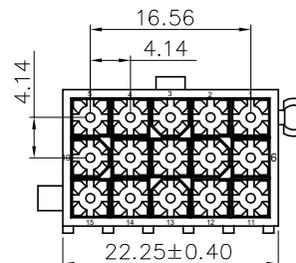
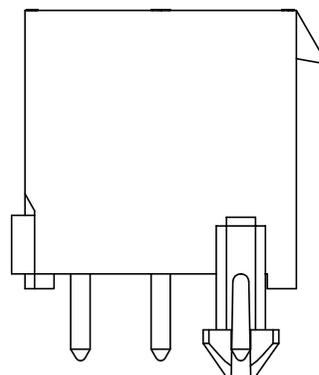
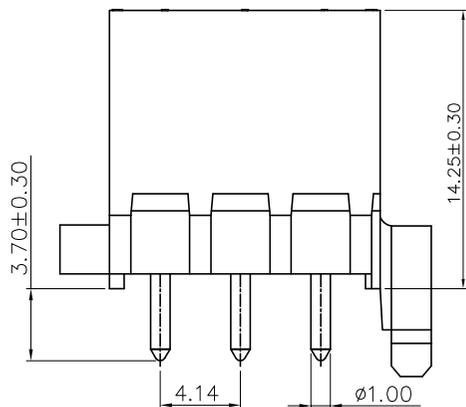


RECOMMENDED LAYOUT FOR 1.57 THICK BOARD

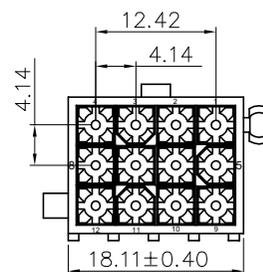
TOLERANCES NON-ACCUMULATIVE

NOTE:

1. MATERIAL SPECIFICATION:
  - 1-1. HOUSING: PA66
  - 1-2. CONTACTS: BRASS
2. PLATING SPECIFICATION:
  - 2-1. CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
3. ELECTRICAL PERFORMANCE:
  - 3-1. CURRENT RATING: 7A
  - RATED VOLTAGE : 600V
  - 3-2. CONTACT RESISTANCE: 20 mΩ MAX
  - 3-3. INSULATION RESISTANCE: 1000MΩ Min
  - 3-4. DIELECTRIC WITHSTANDING : 1500V AC
4. ENVIRONMENTAL PERFORMANCE:
  - 4-1. OPERATING TEMPERATURE: -25°C~+85°C.
5. PACKAGE SPEC: PE BAG
6. P/N:

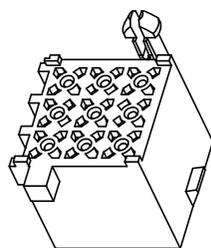
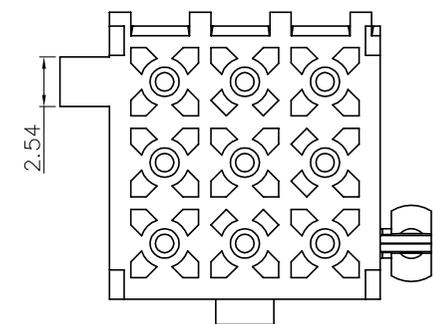


3\*5P  
1:2



3\*4P  
1:2

SERIES NO: C4140 W 0-3 XX 1 X X X HOUSING: 0-UL94V-0  
 CONNECTOR: W-WAFER COLOR: A-BLACK S-NATURE  
 ANGLE: 0-180° PLATING: C-BRIGHT TIN  
 9-90° TERMPOINT: 1-DIP  
 ROW NO: 3-THREE ROWS  
 PIN Q'PY: 09~15



REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:
A0	NEW RELEASE	21.11.17	LINEAR	ANGLES	1:1	Wang_jr	21.11.17	C4140W0-3XX1XXX	ENDE05
			0.00±0.35	X*REF±6°	APPROVED	Han_Gao	21.11.17		
			0.00±0.25	X±3°	DESIGNER	Zijun_Huang	21.11.17	TITLE:	
			0.000±0.10	X*X' ±2°	DRAWN			Pitch 4.14mm 三排 180° DIP Wafer 圆针	

**W** 万连科技  
WanLian Technology Co., Ltd

REV: A0 SHEET: 1/1